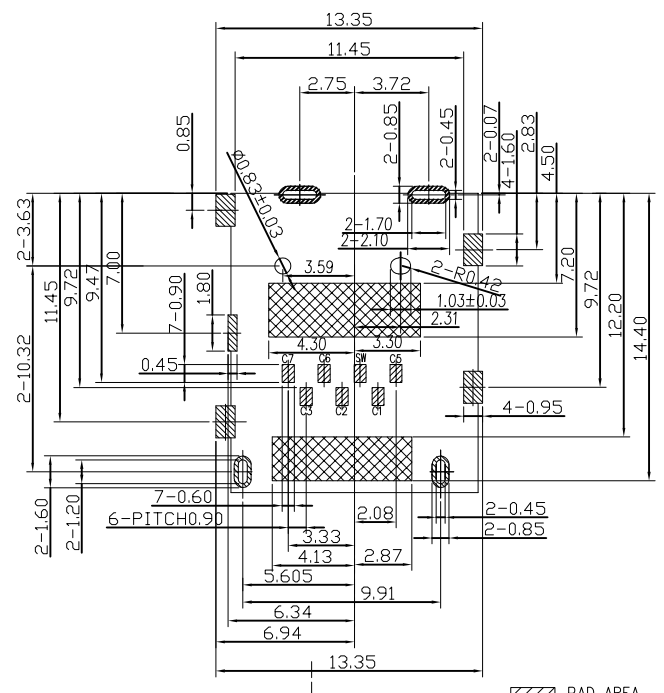
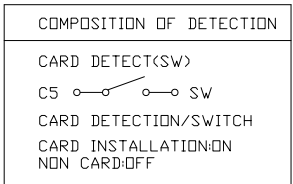
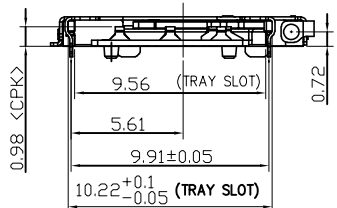
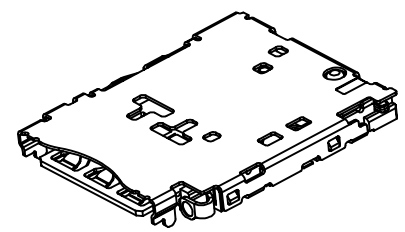
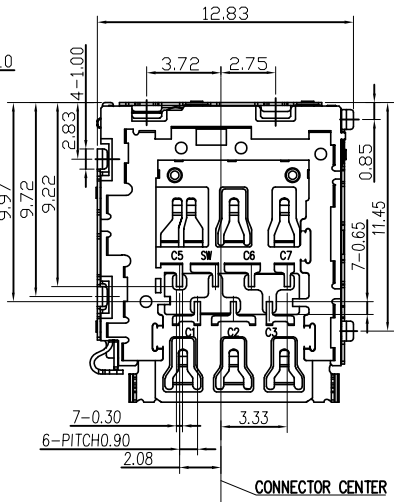
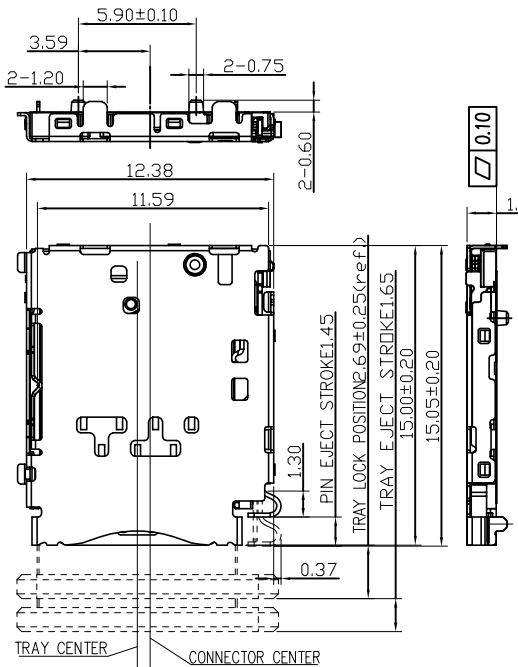


REV.	ECN NO.	DESCRIPTION	DRAW/DATE	CHECKED	APPROVED
------	---------	-------------	-----------	---------	----------



- NOTE:
1. Material:
 - 1-1 Housing: High Temperature Thermoplastic (LCP S475) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
 - 1-3 Cover: SUS304-H T=0.15±0.03mm
 2. Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 3u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 30u" Min.
 - Solder area: Gold 0.8u" Min.
 3. Specification:
 - 3-1 Current Rating: 0.5A max.
 - 3-2 Contact Resistance: 50 mOhms max
 - 3-3 Insulation Resistance: 1000 MOhms min./500VDC
 - 3-4 Dielectric Withstanding Voltage: 500 V AC/1minute
 - 3-5 Operating Temperature: -25°C to +85°C
 - 3-6 Mating Cycles: 5000 Insertions
 4. Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
 5. Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

NAND SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA

SIM Card Pin Assignments

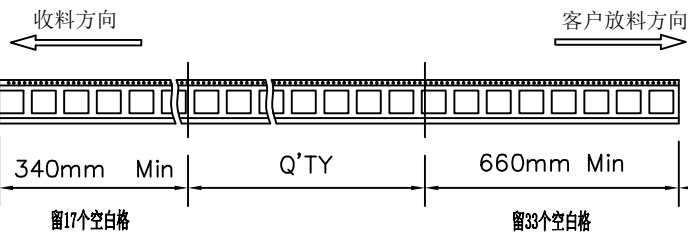
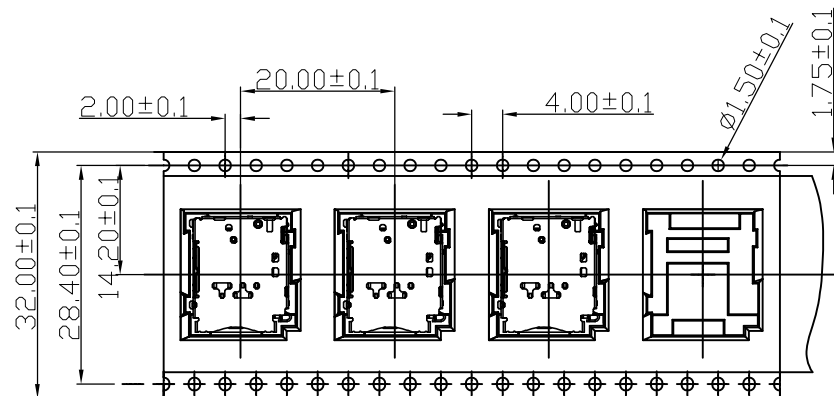
GENERAL TOLERANCES		UNIT	mm		
DISTANCE	X.	±0.25		SEE NOTES	
	.X	±0.20		SEE NOTES	
	.XX	±0.15		APPROVED	KATE DENG
	.XXX	±0.10		CHECKED	KATE DENG
ANGLE	X.	±3.0°		DESIGN	FAND
	.X	±2.0°		DRAWN	Wang Yan
	.XX	±1.0°			

TITLE:		NAND SIM PUSH PULL H1.5 CARD CONN(DIP)			
PART NO.		JK-SP1507AGB003R			
DRAWING NO.					
SCALE	1:1	SIZE	A3	SHEET	1 OF 1
REV.	A				

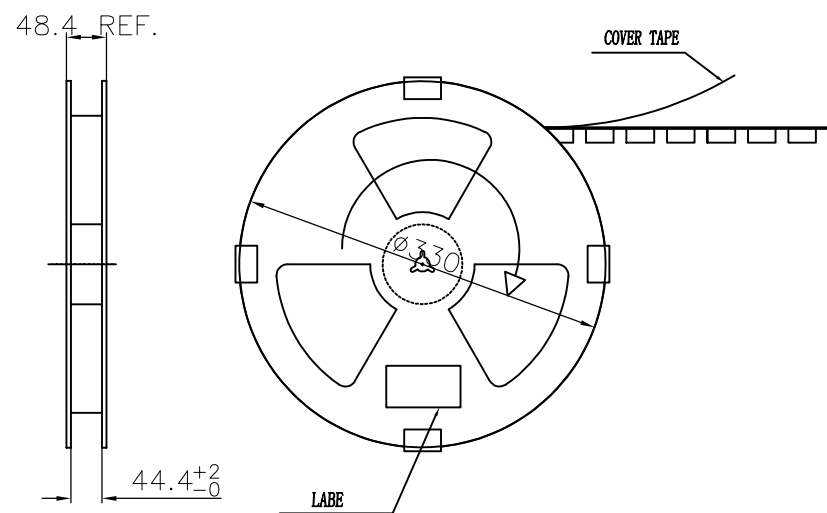
JKF 杰康富精密电子有限公司
J K F precision Electronics Co., LTD

10 9 8 7 6 5 4 3 2 1

〈图一〉



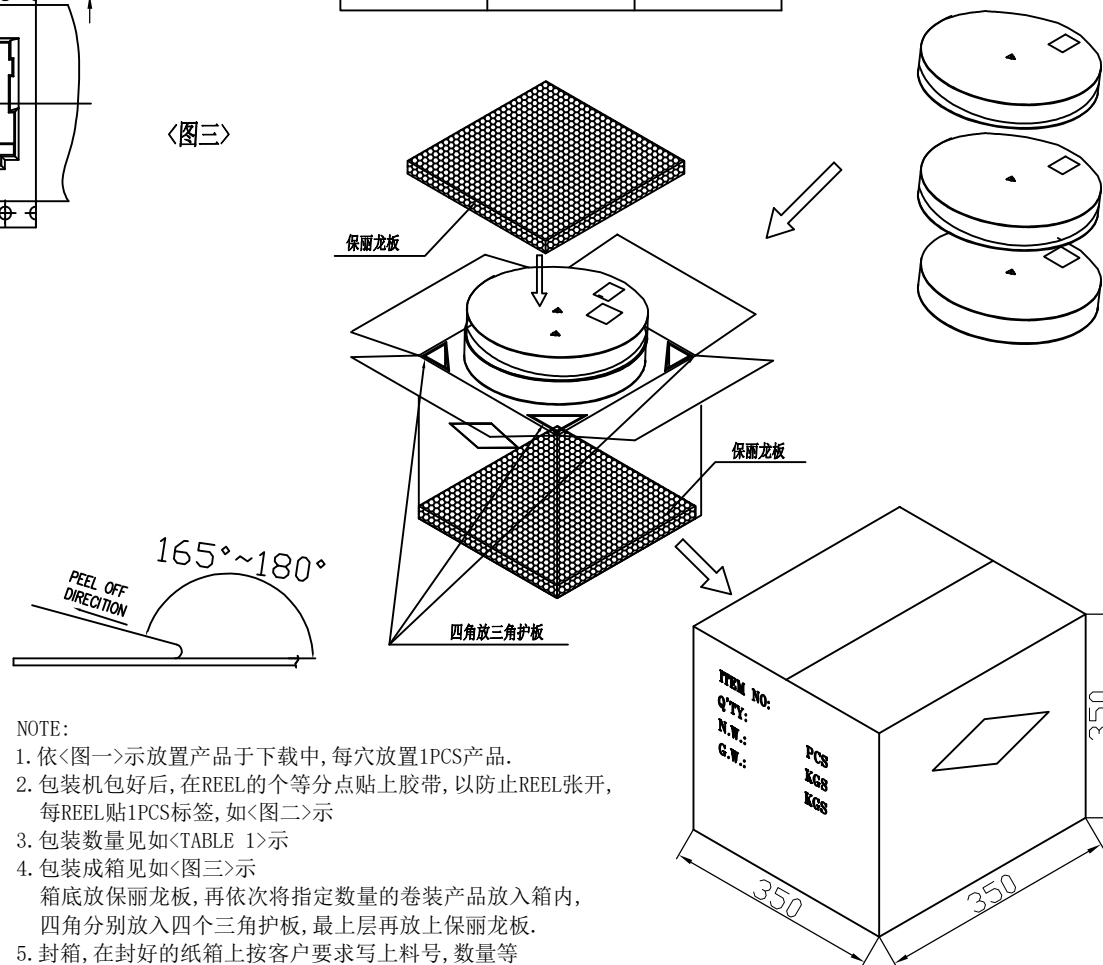
〈图二〉



〈TABLE 1〉 PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
1000	8	8000

〈图三〉



NOTE:

1. 依〈图一〉示放置产品于下载中, 每穴放置1PCS产品.
2. 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如〈图二〉示
3. 包装数量见如〈TABLE 1〉示
4. 包装成箱见如〈图三〉示
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内,
四角分别放入四个三角护板, 最上层再放上保丽龙板.
5. 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

GENERAL TOLERANCES		UNIT	mm		
DISTANCE	X.	±0.25		SEE NOTES	
	.X	±0.20		SEE NOTES	
	.XX	±0.15			
	.XXX	±0.10			
ANGLE	X.	±3.0°			
	.X	±2.0°			
	.XX	±1.0°			
				杰康富精密电子有限公司 J K F precision Electronics Co., LTD	
				TITLE: NAND SIM PUSH PULL H1.5 CARD CONN(DIP)	
				PART NO. JK-SP1507AGB003R	
				DRAWING NO.	
				SCALE 1:1 SIZE A3 SHEET 1 OF 1 REV. A	